

AT5020 Series

Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth

Applications

- ❖ Bluetooth/Wireless LAN/Home RF
- ❖ ISM band 2.4GHz applications



Specifications

Part Number	Frequency Range (MHz)	Peak Gain (XZ-V)	Average Gain (XZ-V)	VSWR	Impedance
AT5020-B2R8HAA_	2400 ~ 2500	0 dBi typ.	-1 dBi typ.	2 max.	50 Ω

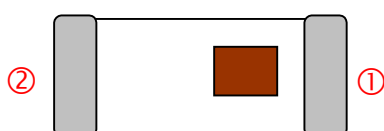
Q'ty/Reel (pcs) : 2,000pcs
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C
 Power Capacity : 3W max.

Part Number

AT 5020 - B 2R8 HAA □ □
① ② ③ ④ ⑤ ⑥ ⑦

① Type	AT : Antenna	② Dimensions (L x W)	5.0x 2.0 mm
③ Material Code	B	④ Frequency Range	2R8=2800MHz
⑤ Specification Code	HAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

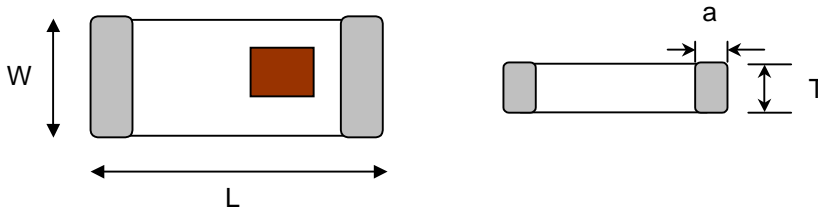
Terminal Configuration



No.	Terminal Name	No.	Terminal Name
①	Feeding Point	②	NC

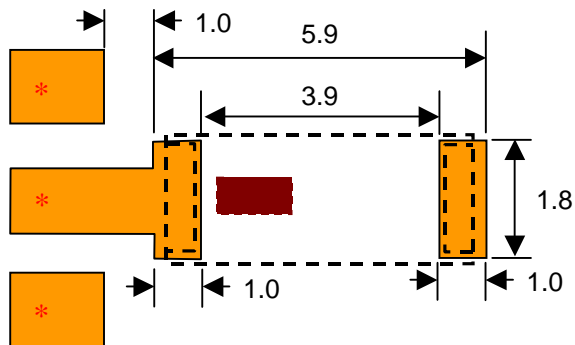
Dimensions and Recommended PC Board Pattern

Unit : mm

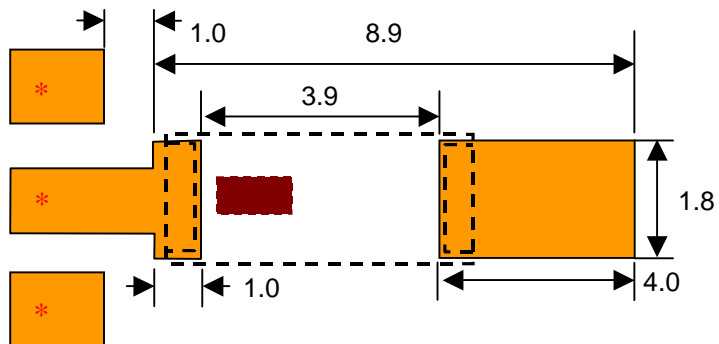


Mark	L	W	T	a
Dimensions	5.0±0.2	2.0±0.2	1.1±0.2	0.5±0.3

(a) Without Matching Circuits



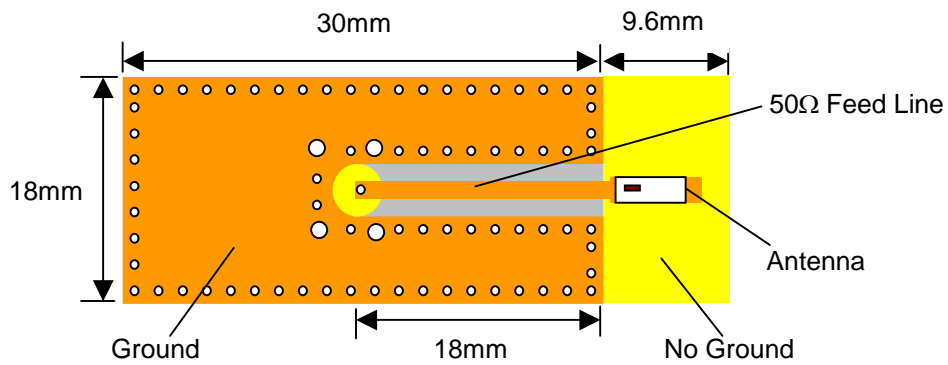
(b) With Matching Circuits



*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

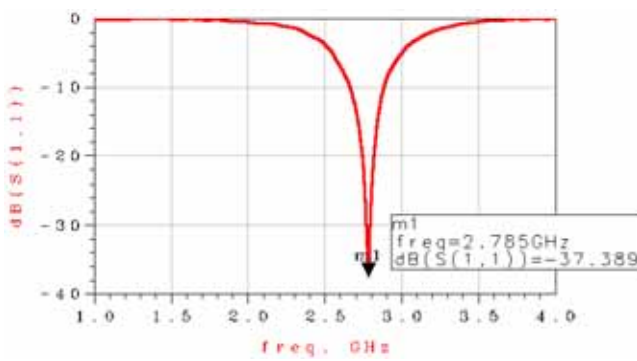
Typical Electrical Characteristics (T=25°C)

❖ Test Board

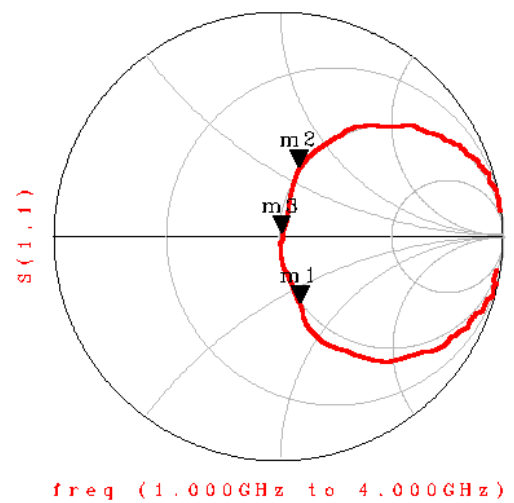
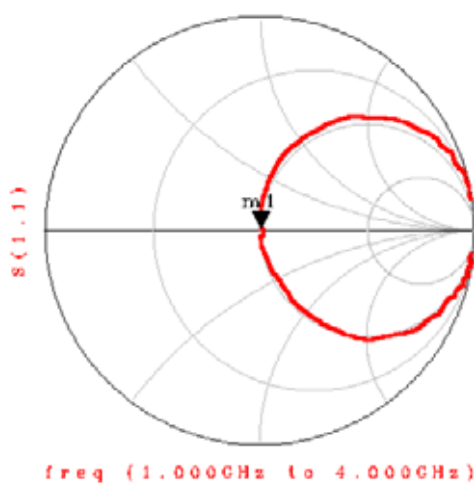
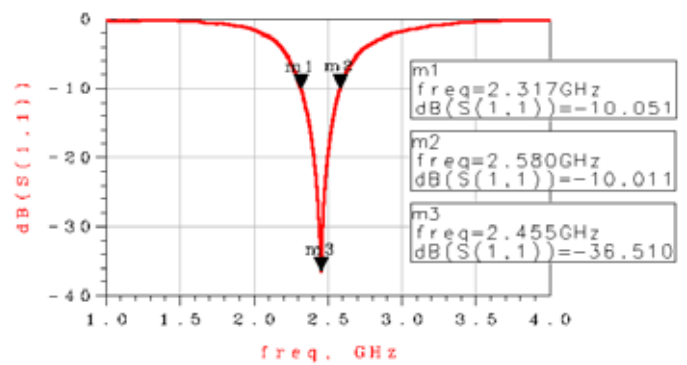


❖ Return Loss

(a) Without Matching Circuits

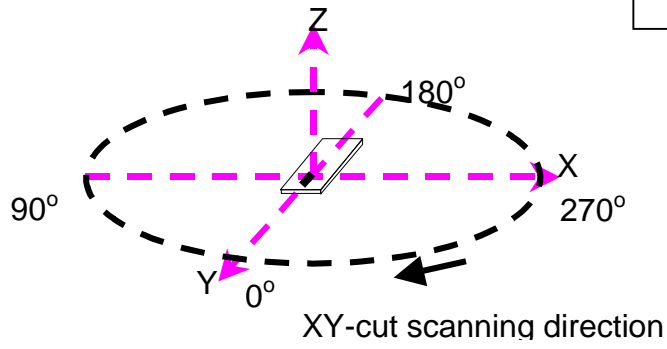


(b) With Matching Circuits

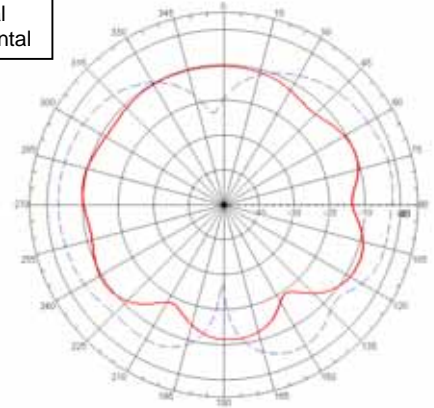


Radiation Patterns

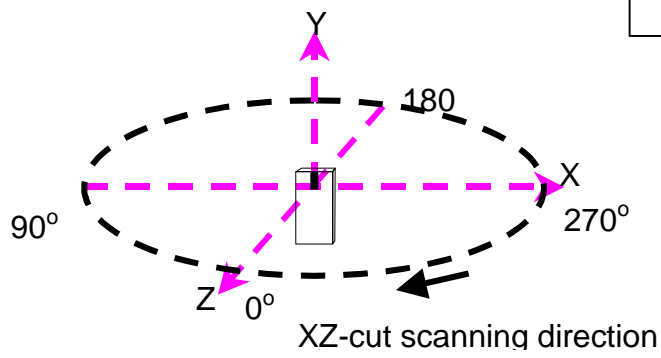
XY-V/XY-H



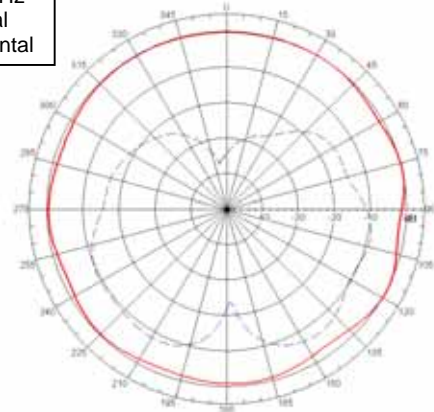
XY cut @2.45GHz
 — Vertical
 - - - Horizontal



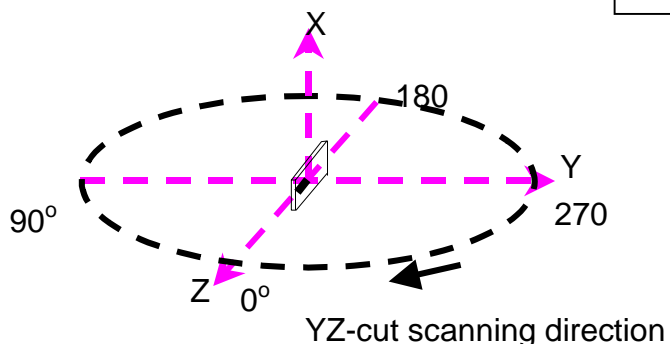
XZ-V/XZ-H



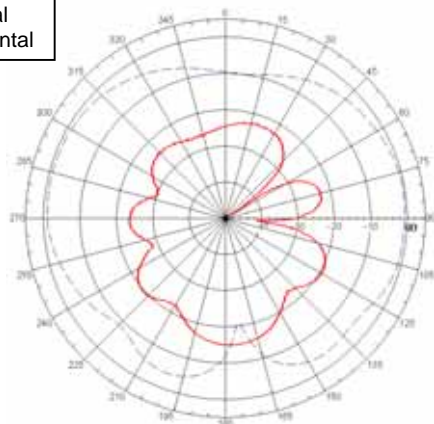
XZ cut @2.45GHz
 — Vertical
 - - - Horizontal



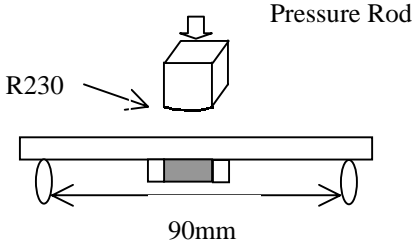
YZ-V/YZ-H



XY cut @2.45GHz
 — Vertical
 - - - Horizontal

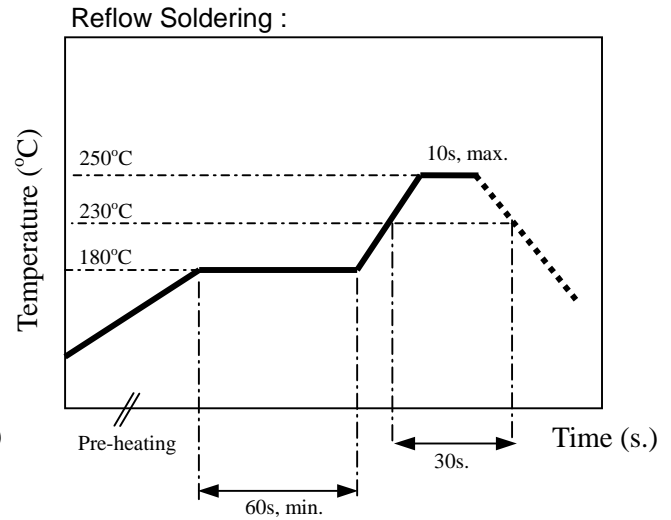
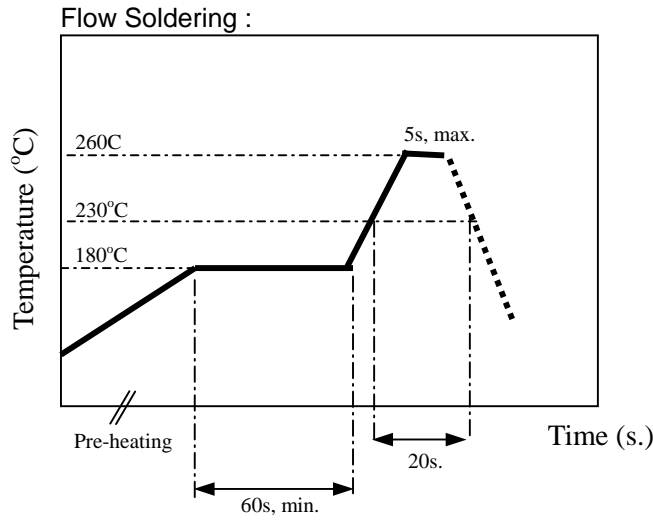


Mechanical & Environmental Characteristics

	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 75% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $230 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/ step 1: $85 \pm 5^\circ\text{C}$ for 20sec step 2: $-40 \pm 3^\circ\text{C}$ for 20sec Cycle time: 30min No. of cycles: 100 Recovery: 1-2hrs
Heat Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Duration: 24 ± 2hrs Recovery: 1-2hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 24 ± 2hrs Recovery: 1-2hrs
Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 80% ~ 85% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Soldering strength (Push strength)	<ol style="list-style-type: none"> 9.8N minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Bending)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection 
Drop Shock	<ol style="list-style-type: none"> No apparent damage 	<ol style="list-style-type: none"> Dropped onto hard wood from height of 50 cm for 3 times ; each x,y and z direction except terminal direction

Typical Soldering Profile

❖ Typical Soldering Profile for Lead-free Process



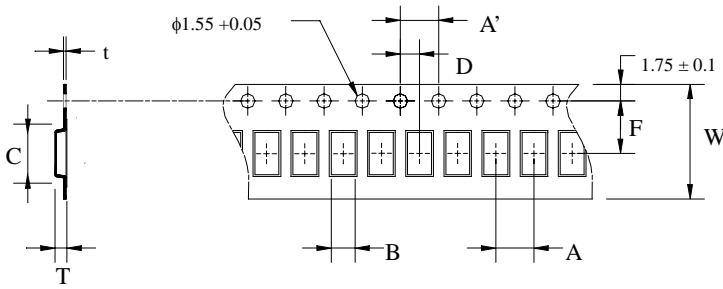
The sample must be pre-heated before soldering .The temperature difference between preheating and soldering must be within 150 .

Notes

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

Taping Specifications

❖ Tape Dimensions (Unit: mm)

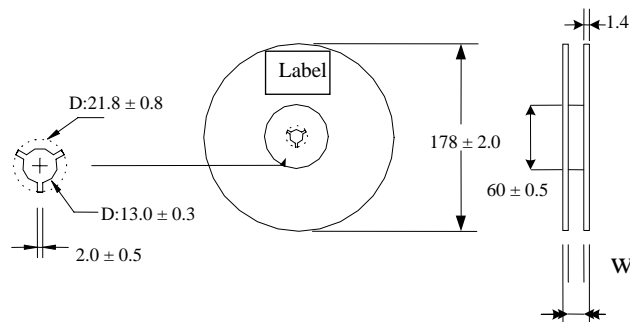


Type	A	A'	B	C	D	t	T	F	W
5020	4.0±0.1	4.0±0.1	2.4±0.1	5.4±0.1	2.0±0.1	0.25±0.05	Max. 1.4	5.5±0.1	12.0±0.1

❖ Quantity

Type	5020
Quantity /per reel	2,000

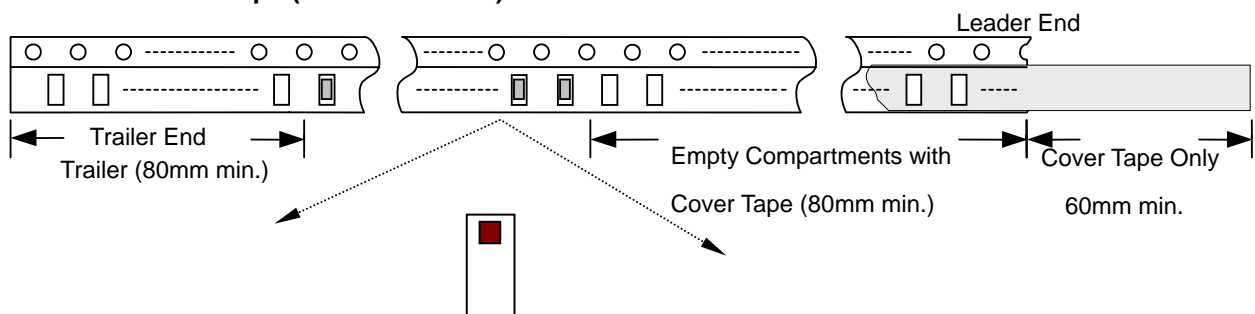
❖ Reel Dimensions (Unit: mm)



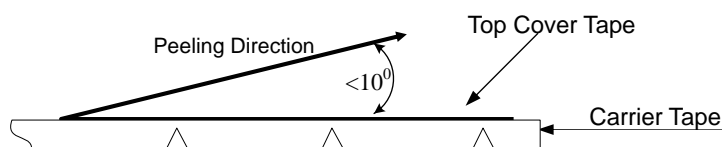
Label: Customer's Name, ACX P/N, Q'ty, Date, ACX Corp.

19.5

❖ Leader and Trailer Tape (Plastic material)



❖ Peel-off Force



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300±10 mm/min .

❖ **Storage Conditions**

- (1) Temperature: 15 ~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment
- (3) Products should be used within six months of receipt.

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Manufacturer: ADVANCED CERAMIC X CORP.

Address: No.165, Hanyang Road, Hsinchu Industrial District, Hsinchu Hsien, Taiwan